



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et. al

Serial No.: 10/648,654

Filed: August 26, 2003

For: METHODS FOR STRESS
REDUCTION FEATURE FOR LOC LEAD
FRAME

Confirmation No.: 3870

Examiner: J. Fischer

Group Art Unit: 1733

Attorney Docket No.: 2269-2739.6US
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Sir:

Please amend the above-referenced application as follows:

Amendments to the Title begin on page 3 of this paper;

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Amendments to the Specification begin on page 4 of this paper;

Amendments to the Claims are set forth in the listing of the claims that begins on page 7 of this paper;

Corrections to the Drawings are summarized on page 17 of this paper, with a replacement sheet and an annotated sheet showing the corrections enclosed herewith; and

Remarks start at page 18 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

METHODS ASSEMBLY METHOD FOR SEMICONDUCTOR DIE AND STRESS REDUCTION FEATURE FOR LOC LEAD FRAME